ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.						This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1					Form Type Distribute											
Supplier	Informa	tion														
Company	Company name*				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2024-05-16				
Contact Name				Title - Contac	Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards				Product Envi	ro Compliance		NA					Product-Env-Stewards@onsemi.com				
Authorized	Authorized Representative*				Title - Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards				Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item			Number Mfr Item Name				Effective Date	Version	Manu	Manufacturing Site		Weight*	UOM	Unit Type	
	FAN322			4TUMX-F085 Low-Side Gate Driver SO8				2024-05-16		TH2	TH2		79.2153	mg	Each	
Manufacturing Process Information																
Terminal Plating / Grid Array Material				Terminal Base Alloy J-STD-020 MS			L Rating	ng Peak Process Body Temperature Max Time at Pea			Iax Time at Peak	k Temperature Number of Reflow Cycles				
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 3		3		260 C		C 30	30 seco		conds 3			
Comments																
ATTENTION: MSL 3 Rated item requires Bake and Dry Pack (after electrical test)																
For more information regarding material composition please refer to page 3																

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Iability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.4418	mg	Supplier	Silicon (Si)	7440-21-3		1.4418	mg
Die Attach	0.2109	mg	Supplier	Ethylene glycol dicyclopentenyl ether methacrylate	68586-19-6		0.0074	mg
			Supplier	Bis(a,a-dimethylbenzyl) Peroxide	80-43-3		0.0014	mg
			Supplier	Silver (Ag)	7440-22-4		0.2021	mg
Lead Frame	29.8891	mg	Supplier	Zinc (Zn)	7440-66-6		0.0359	mg
			Supplier	Iron (Fe)	7439-89-6		0.7024	mg
			Supplier	Copper (Cu)	7440-50-8		29.1419	mg
			Supplier	Phosphorus (P)	7723-14-0		0.009	mg
Mold Compound-Black	47.026	mg		Epoxy resin	proprietary data		2.8216	mg
			Supplier	Phenolic Resin	Proprietary Data		2.8216	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2351	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.9721	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1756	mg
Plating	0.4175	mg	Supplier	Palladium (Pd)	7440-05-3		0.0142	mg
			В	Nickel (Ni)	7440-02-0		0.3985	mg
			Supplier	Gold (Au)	7440-57-5		0.0048	mg
Wire Bond - Au	0.23	mg	Supplier	Gold (Au)	7440-57-5		0.23	mg